

IN THE CLAIMS:

1. (Currently Amended) An implantable device including a feedthrough assembly disposed within a hermetically sealed housing of the implantable device and having a temperature sensor, and said ~~implantable device~~feedthrough assembly comprising:
 - a sleeve outer portion hermetically bonded to the housing;
 - a thermal insulator disposed within the sleeve outer portion;
 - a pin spaced from the housing and at least partially disposed within the thermal insulator; and
 - a temperature sensor disposed within the pin.
2. (Previously Presented) The device of claim 1, wherein the implantable device is a pacemaker cardioverter defibrillator.
3. (Original) The device of claim 1, wherein the implantable device is a lead.
4. (Original) The device of claim 1, wherein the pin includes an hollow interior and the temperature sensor is disposed within the hollow interior.
5. (Original) The device of claim 4, wherein the temperature sensor is in contact with an interior surface of the pin.
6. (Original) The device of claim 4, further comprising a thermal barrier disposed within the hollow interior and isolating the temperature sensor from an interior of the housing.
7. (Original) The device of claim 6, wherein the thermal barrier extends beyond the hollow interior of the pin and into the interior of the housing.
8. (Original) The device of claim 1, further comprising a sleeve inner portion disposed between the pin and the thermal insulator.

9. (Currently Amended) An implantable device including a feedthrough assembly disposed within a hermetically sealed housing of the implantable device comprising:

means for sensing a physical parameter disposed within a pin; and
means for hermetically sealing the pin.

10. (Original) The device of claim 9, wherein means for sensing is a temperature sensor.

11. (Currently Amended) A feedthrough assembly comprising:

a sleeve positionable within an opening through a housing of an implantable medical device and hermetically sealable to the housing;
an insulator disposed within the sleeve and hermetically sealed thereto;
a pin disposed within and hermetically sealed to the ~~insulator~~insulating ring, the pin including a hollow, fluid filled interior, a first membrane configured to be exposed to an external medium, and a second membrane ~~operably adapted to be coupled~~ with a sensor positionable within the housing, wherein a physical parameter of the second membrane is sensed by the sensor and correlates for correlation to a pressure within the external medium.

12. (Previously presented) The feedthrough of claim 11, wherein a surface area of the first membrane is smaller than a surface area of the second membrane.